



REPLACEMENT SHEET

Title: INTERCONNECT FOR ELECTRICALLY CONNECTING A MULTICHIP MODULE TO A CIRCUIT SUBSTRATE AND PROCESSES FOR MAKING AN USING SAME
Inventor: Adams et al. Docket No.: 58689-8074.US02
Perkins Cole LLP (650) 838-4300

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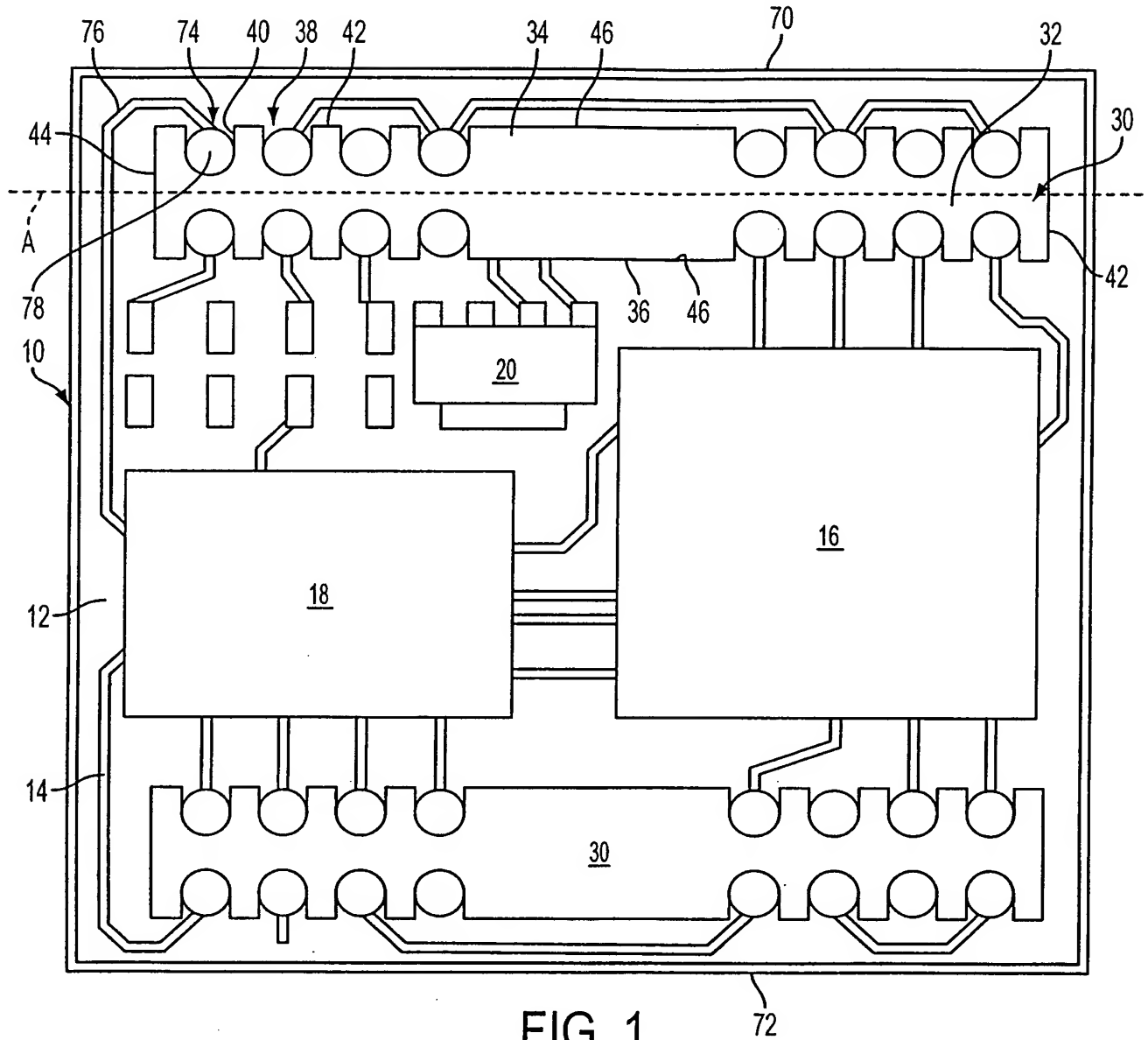


FIG. 1

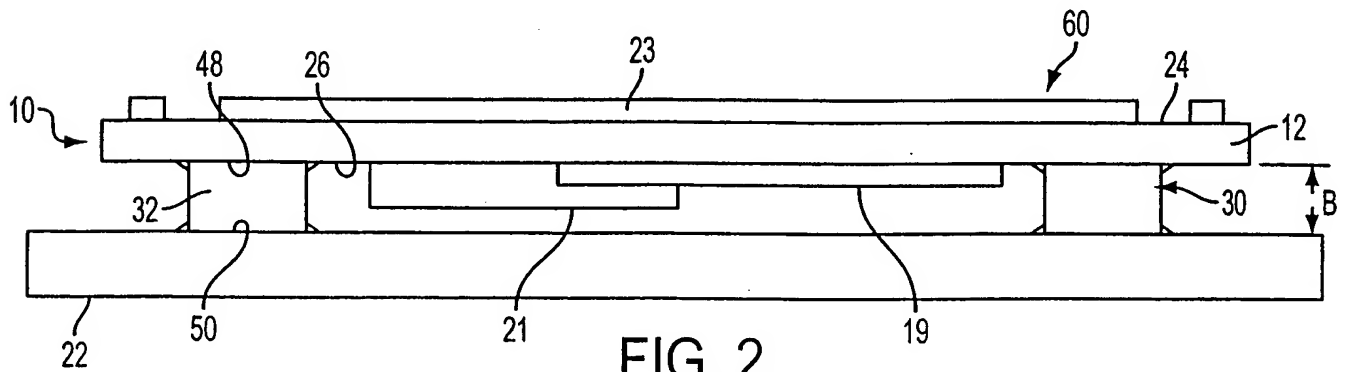


FIG. 2

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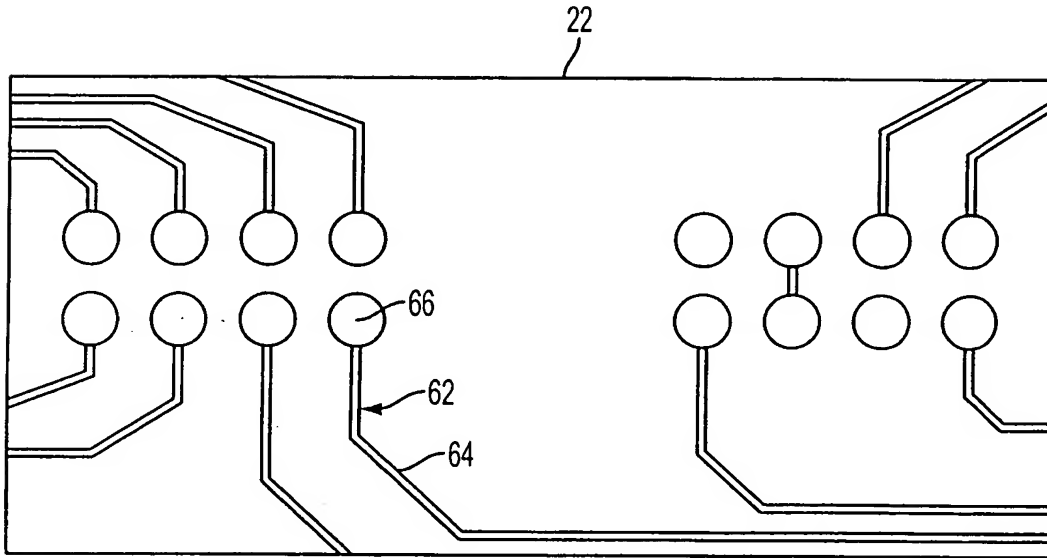


FIG. 3

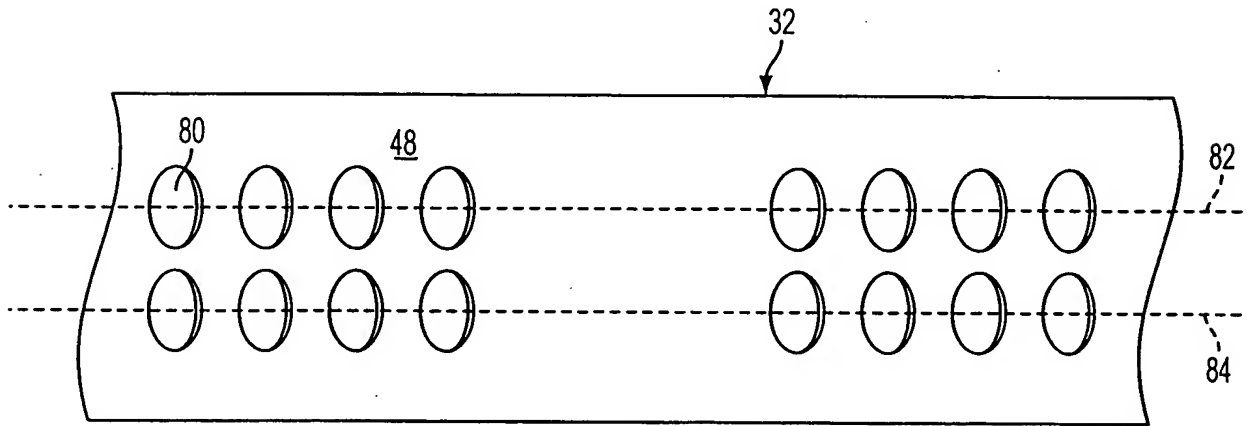


FIG. 4

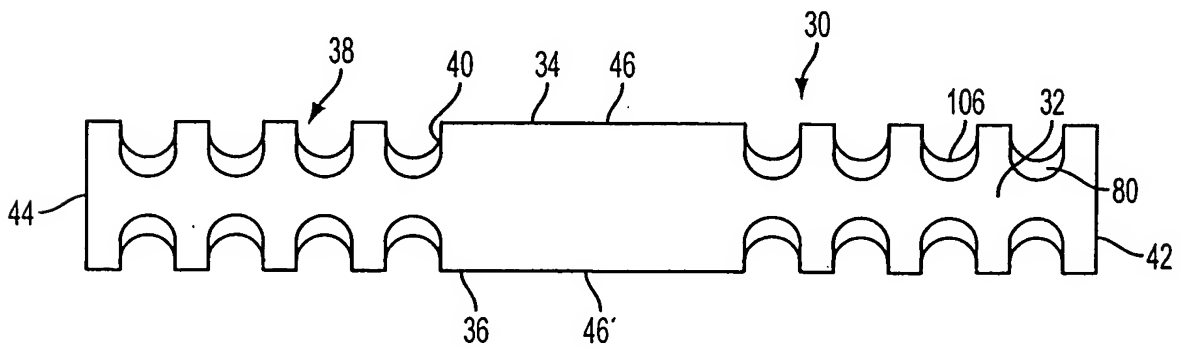


FIG. 8

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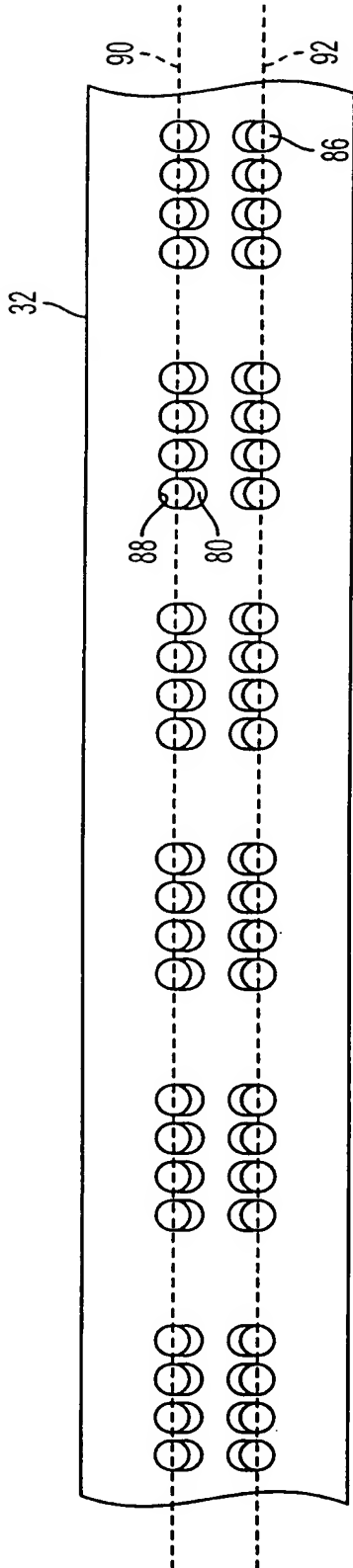


FIG. 5

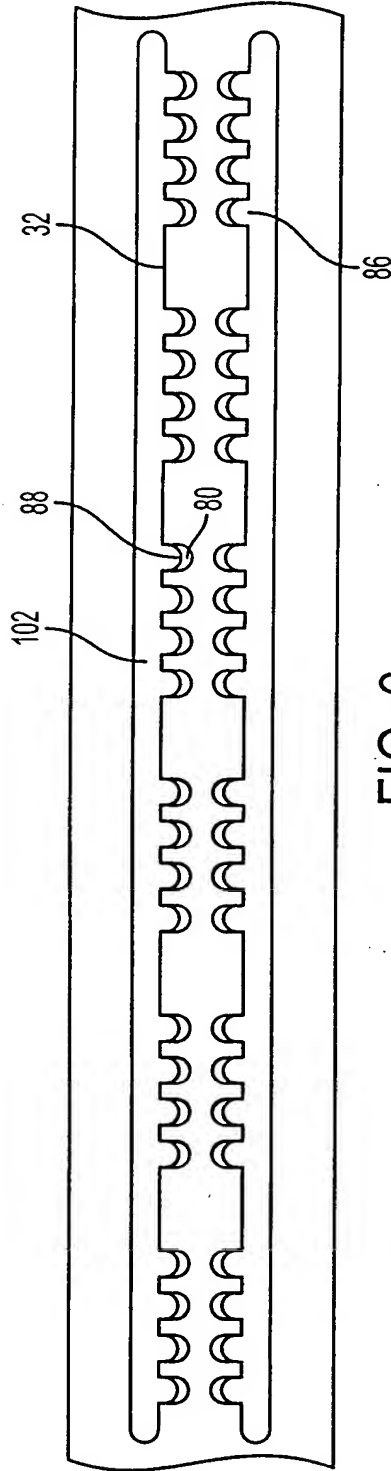


FIG. 6

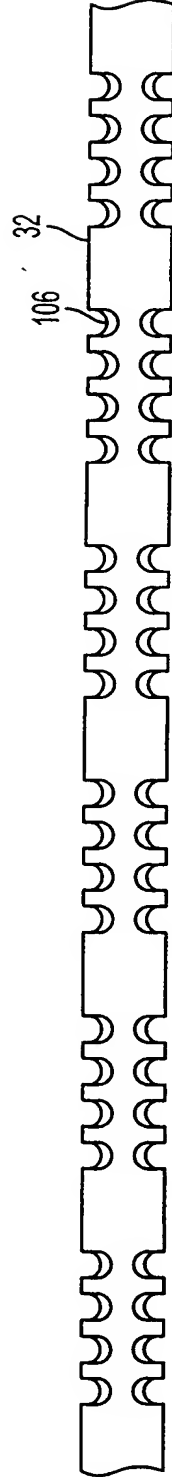


FIG. 7

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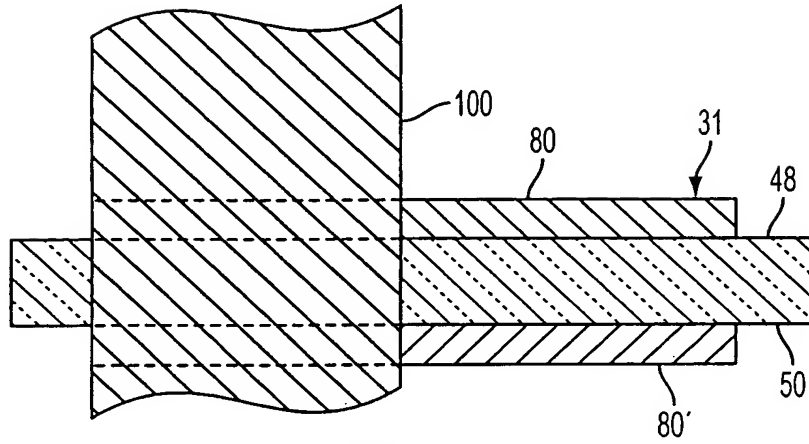


FIG. 9

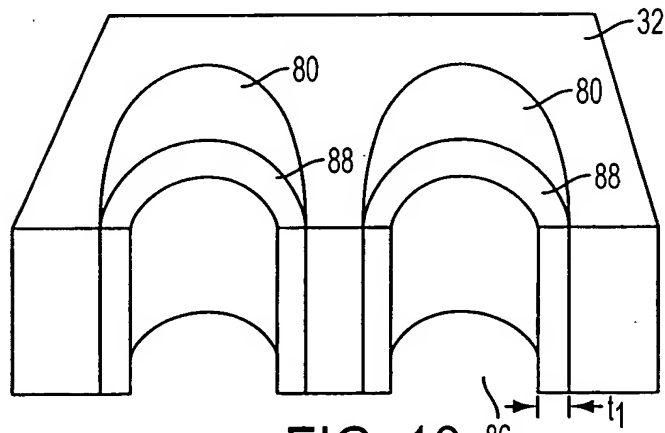


FIG. 10

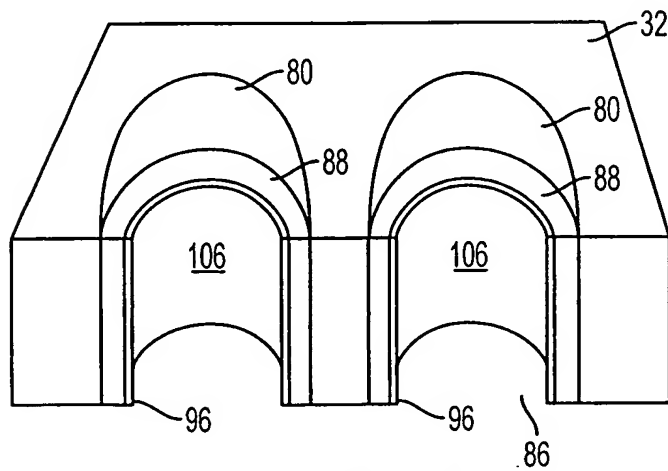


FIG. 11

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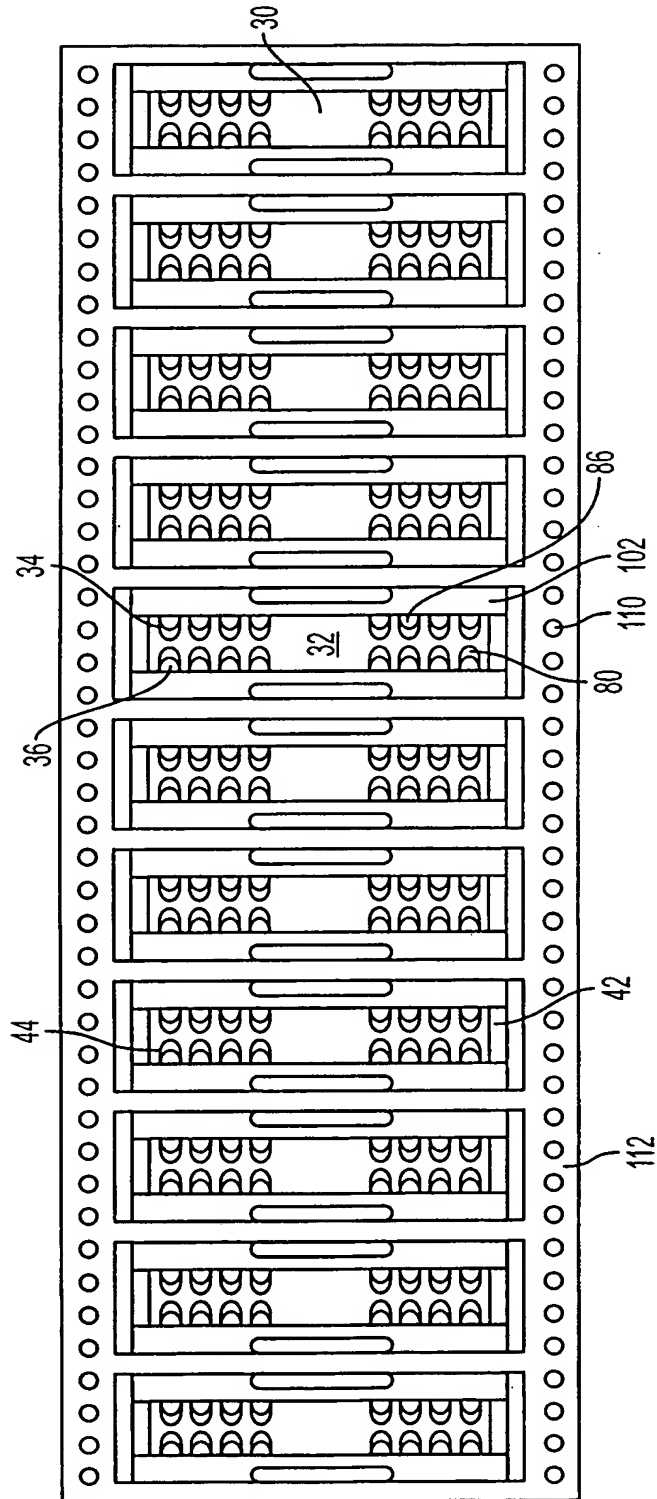


FIG. 12